

## Multilayer Ceramic Chip Capacitors

## CGA8P1C0G3F331K250KE



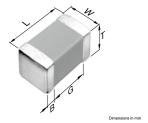






#### TDK item description CGA8P1C0G3F331KT\*\*\*S

Applications	Automotive Grade
Feature	High High Voltage (1000V and over)  Soft Soft Termination  AEC-Q200 AEC-Q200
Series CGA8(4532) [EIA 1812]	
Status	Production



Size		
Length(L)	4.50mm +0.50,-0.40mm	
Width(W)	3.20mm ±0.40mm	
Thickness(T)	2.50mm ±0.30mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)		
Recommended Land Pattern (PA)	3.10mm to 3.70mm	
Recommended Land Pattern (PB)	1.20mm to 1.40mm	
Recommended Land Pattern (PC)	2.40mm to 3.20mm	
Recommended Slit Pattern (SD)	1.00mm to 1.30mm	

Electrical Characteristics		
Capacitance	330pF ±10%	
Rated Voltage	3kVDC	
Temperature Characteristic	C0G(0±30ppm/°C)	
Q (Min.)	1000	
Insulation Resistance (Min.)	10000ΜΩ	

Other		
Soldering Method	Reflow	
AEC-Q200	Yes	
Packing	Blister (Plastic)Taping [180mm Reel]	
Package Quantity	500pcs	

<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

#### CGA8P1C0G3F331K250KE

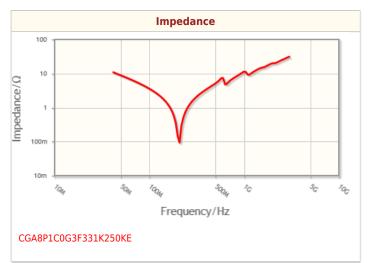


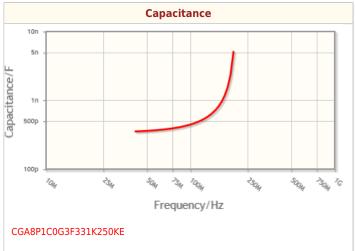


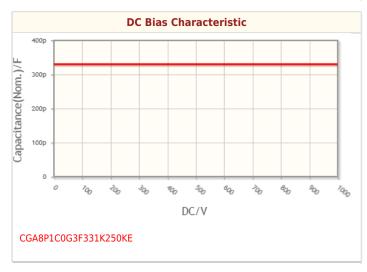


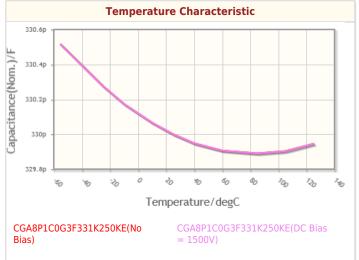


# Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)









 $<sup>!\ \</sup>mbox{Images}$  are for reference only and show exemplary products.

<sup>!</sup> This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.

## CGA8P1C0G3F331K250KE

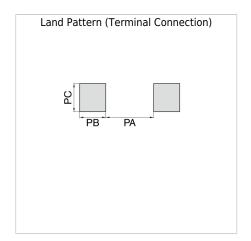








# **Associated Images**



<sup>!</sup> Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

<sup>!</sup> All specifications are subject to change without notice.